



Product Change Notification

Change Notification #: 117897 - 00
Change Title: Minor Change
Select Intel® Xeon®, Intel® Core™ and
Boxed Intel® Core™ Processors,
PCN 117897-00, Product Material,
Visual Appearance Change to Lidded Products
Date of Publication: November 25, 2020

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	February 25, 2021
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Description of Change to the Customer:

Due to tooling end-of-life constraints, discontinuing supplier support and process simplification, Intel will be changing their process for placing lids during the cure portion of the assembly process. This change will result in the following two visual changes to the package:

- There will be some additional sealant on the edge where the Lid meets the substrate
- There will be a break in the sealant placed on the substrate just under the lid

Note: The lid process referred to as "old placement process" in the pictures below uses an older technology placed by a specific tool that will end of life. The process referred to below as the "new placement process" although similar, is the next generation. Both the old placement process and the new placement process attach lids to units, accomplishing the same function. However, moving to the new placement process results in the two changes named within this notification.

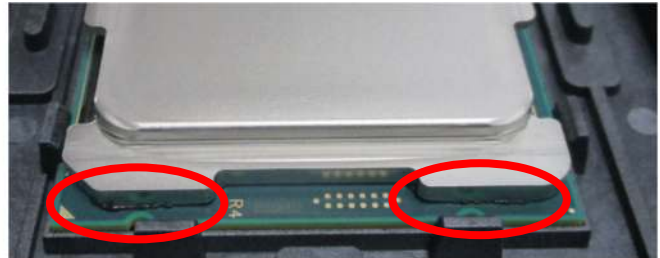
1. Additional Sealant noticeable on edge where substrate and lid meet, causing a squished-out appearance.

Old Placement Process



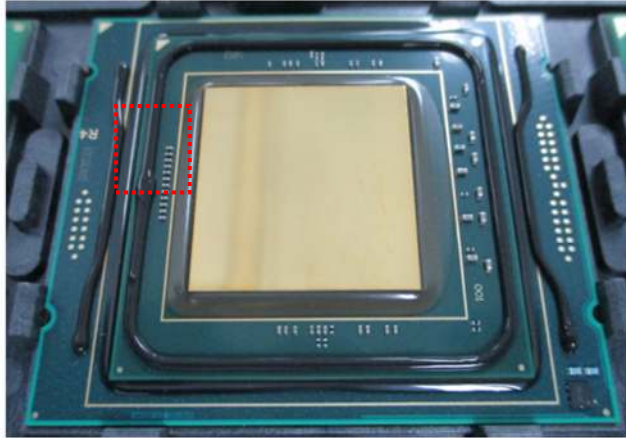
(pictures are for reference only)

New Placement Process



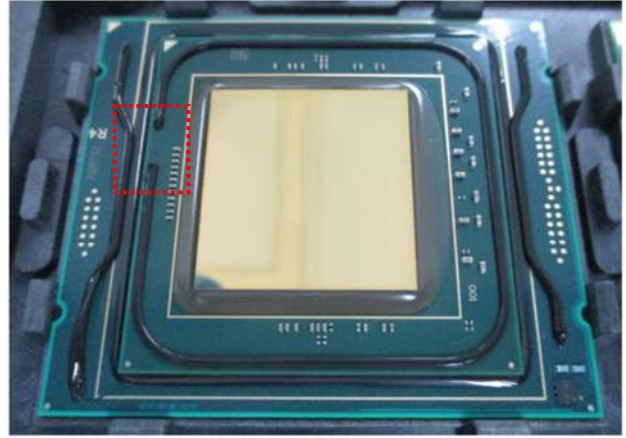
2. A break in the sealant opening on the substrate on the underside of the lid

Old Placement Process



Sealant enclosed

New Placement Process



Sealant Opening

(pictures for reference only)

These minor changes are visible to the customer upon inspection and will occur on the Select Intel® Xeon®, Intel® Core™ and Boxed Intel® Core™ Processors listed in the Products Affected / Intel Ordering Codes table below.

Customer Impact of Change and Recommended Action:

This is a Minor change. There is no change to the Form, Fit or Function of the product as a result of this change. This is strictly a result of using different toolsets to accomplish the same task. Customers do not need to do anything as a result of this change.

Intel will not do a hard transition off of the old placement process to the new placement process. Therefore, customers should expect to see a limited mixture of finished goods until fully transitioned. The changes will start as early as February 25, 2021 as noted above.

Once Intel begins to transition, the older placement process will be discontinued and only the new process will be in place.

Please contact your Intel Representative with any questions or concerns regarding the change detailed in this notification.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	Stepping	S-Spec	MM#
Intel® Core i9-9980XE Extreme Edition	CD8067304126600	M0	S REZ3	986447
Intel® Core™ i9-9960X X-series Processor	CD8067304126500	M0	S REZ4	986448
Intel® Core™ i9-9940X X-series Processor	CD8067304175600	M0	S REZ5	986449
Intel® Core™ i9-9920X X-series Processor	CD8067304126300	M0	S REZ6	986450
Intel® Core™ i9-9900X X-series Processor	CD8067304126200	M0	S REZ7	986451
Intel® Core™ i9-9820X X-series Processor	CD8067304126901	M0	S REZ8	986452
Intel® Core™ i7-9800X X-series Processor	CD8067304126100	M0	S REZ9	986453
Boxed Intel® Core™ i7-9800X X-series	BX80673179800X	M0	S REZ9	999AC3
Boxed Intel® Core™ i9-9900X X-series	BX80673199900X	M0	S REZ7	999AC5
Boxed Intel® Core™ i9-9920X X-series	BX80673199920X	M0	S REZ6	999AC6

Marketing Name	Product Code	Stepping	S-Spec	MM#
Boxed Intel® Core™ i9-9960X X-series	BX80673I99960X	M0	S REZ4	999AC7
Boxed Intel® Core™ i9-9820X X-series	BX80673I99820X	M0	S REZ8	999AC8
Boxed Intel® Core™ i9-9940X X-series	BX80673I99940X	M0	S REZ5	999AC9
Boxed Intel® Core™ i9-9980XE Processor	BXC80673I99980X	M0	S REZ3	999ACD
Boxed Intel® Core™ i9-9960X X-series	BXC80673I99960X	M0	S REZ4	999ACF
Boxed Intel® Core™ i9-9940X X-series	BXC80673I99940X	M0	S REZ5	999ACG
Boxed Intel® Core™ i9-9920X X-series	BXC80673I99920X	M0	S REZ6	999ACJ
Boxed Intel® Core™ i9-9900X X-series	BXC80673I99900X	M0	S REZ7	999ACK
Boxed Intel® Core™ i9-9820X X-series	BXC80673I99820X	M0	S REZ8	999ACL
Boxed Intel® Core™ i7-9800X X-series	BXC80673I79800X	M0	S REZ9	999ACM
Boxed Intel® Core™ i9-9980XE Processor	BX80673I99980X	M0	S REZ3	999AD1
Intel® Xeon® Silver 4214 Processor	CD8069504212601	L1	S RFB9	999CM1
Intel® Xeon® Silver 4215 Processor	CD8069504212701	L1	S RFBA	999CM2
Intel® Xeon® Silver 4216 Processor	CD8069504213901	L1	S RFBB	999CM3
Intel® Xeon® Gold 5215 Processor	CD8069504214002	L1	S RFBC	999CM4
Intel® Xeon® Gold 5215M Processor	CD8069504214102	L1	S RFBD	999CM5
Intel® Xeon® Gold 5215L Processor	CD8069504214202	L1	S RFBE	999CM6
Intel® Xeon® Gold 5217 Processor	CD8069504214302	L1	S RFBF	999CM7
Intel® Xeon® Gold 5220 Processor	CD8069504214601	L1	S RFBJ	999CMA
Intel® Xeon® Silver 4214Y Processor	CD8069504294401	L1	S RFDG	999DKL
Intel® Xeon® Gold 5218B Processor	CD8069504295701	L1	S RFDJ	999DKN
Intel® Xeon® Silver 4214R Processor	CD8069504343701	L1	S RG1W	999H4H
Boxed Intel® Xeon® Silver 4214 Processor	BX806954214	L1	S RFB9	999H7T
Boxed Intel® Xeon® Silver 4216 Processor	BX806954216	L1	S RFBB	999H7W
Boxed Intel® Xeon® Gold 5220 Processor	BX806955220	L1	S RFBJ	999H7X
Intel® Xeon® Gold 5218N Processor	CD8069504384601	L1	S RGLN	999KGL
Boxed Intel® Xeon® Silver 4214R Processor	BX806954214R	L1	S RG1W	999PTH

PCN Revision History:

Date of Revision:

November 25, 2020

Revision Number:

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Reason:

Originally Published PCN



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117897 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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